

MITSUBISHI LSIs

MH4M36CJD-5,-6,-7

FAST PAGE MODE (4194304-WORD BY 36-BIT) DYNAMIC RAM

DESCRIPTION

The MH4M36CJD is an 4M word by 36-bit dynamic RAM module and consists of 8 industry standard 4M X 4 dynamic RAMs in TSOP and 4 industry standard 4M X 1 dynamic RAMs in TSOP.

The ICs are mounted on both sides of small ceracom PC boards and form a convenient 64-pin WDIP package.

FEATURES

Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
MH4M36CJD-5	50	13	25	13	90	7240
MH4M36CJD-6	60	15	30	15	110	5920
MH4M36CJD-7	70	20	35	20	130	5200

- Utilizes industry standard 4M X 4 DRAMs in TSOP package and 4M X 1 DRAMs in TSOP package
- Single 5V $\pm$ 10% supply
- Low stand-by power dissipation
66mW (Max) CMOS Input level
- Low operating power dissipation
MH4M36CJD - 5 9.15W (Max)
MH4M36CJD - 6 7.48W (Max)
MH4M36CJD - 7 6.51W (Max)
- All inputs, output TTL compatible and low capacitance
- 2048 refresh cycles every 32ms (A₀ ~ A₁₀)
- Includes 12 0.22uF decoupling capacitors

APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

PIN CONFIGURATION (TOP VIEW)

DQ0	1		64	DQ16
DQ1	2		63	DQ17
DQ2	3		62	DQ18
DQ3	4		61	DQ19
DQ4	5		60	Vcc
DQ5	6		59	DQ20
Vss	7		58	DQ21
DQ6	8		57	DQ22
DQ7	9		56	DQ23
DQP0	10		55	DQP2
/CAS0	11		54	/CAS2
DQ8	12		53	Vss
DQ9	13		52	DQ24
Vcc	14		51	DQ25
DQ10	15		50	DQ26
DQ11	16		49	DQ27
DQ12	17		48	DQ28
DQ13	18		47	DQ29
DQ14	19		46	Vcc
DQ15	20		45	DQ30
Vss	21		44	DQ31
DQP1	22		43	DQP3
/CAS1	23		42	/CAS3
A0	24		41	/RAS0
A1	25		40	RFU
A2	26		39	Vss
A3	27		38	/W
Vcc	28		37	RFU
A4	29		36	RFU
A5	30		35	A10
A6	31		34	A9
A7	32		33	A8

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FUNCTION

The MH4M36CJD provide, in addition to normal read and write a number of other functions,

e.g., fast page mode, $\overline{\text{RAS}}$ -only refresh.

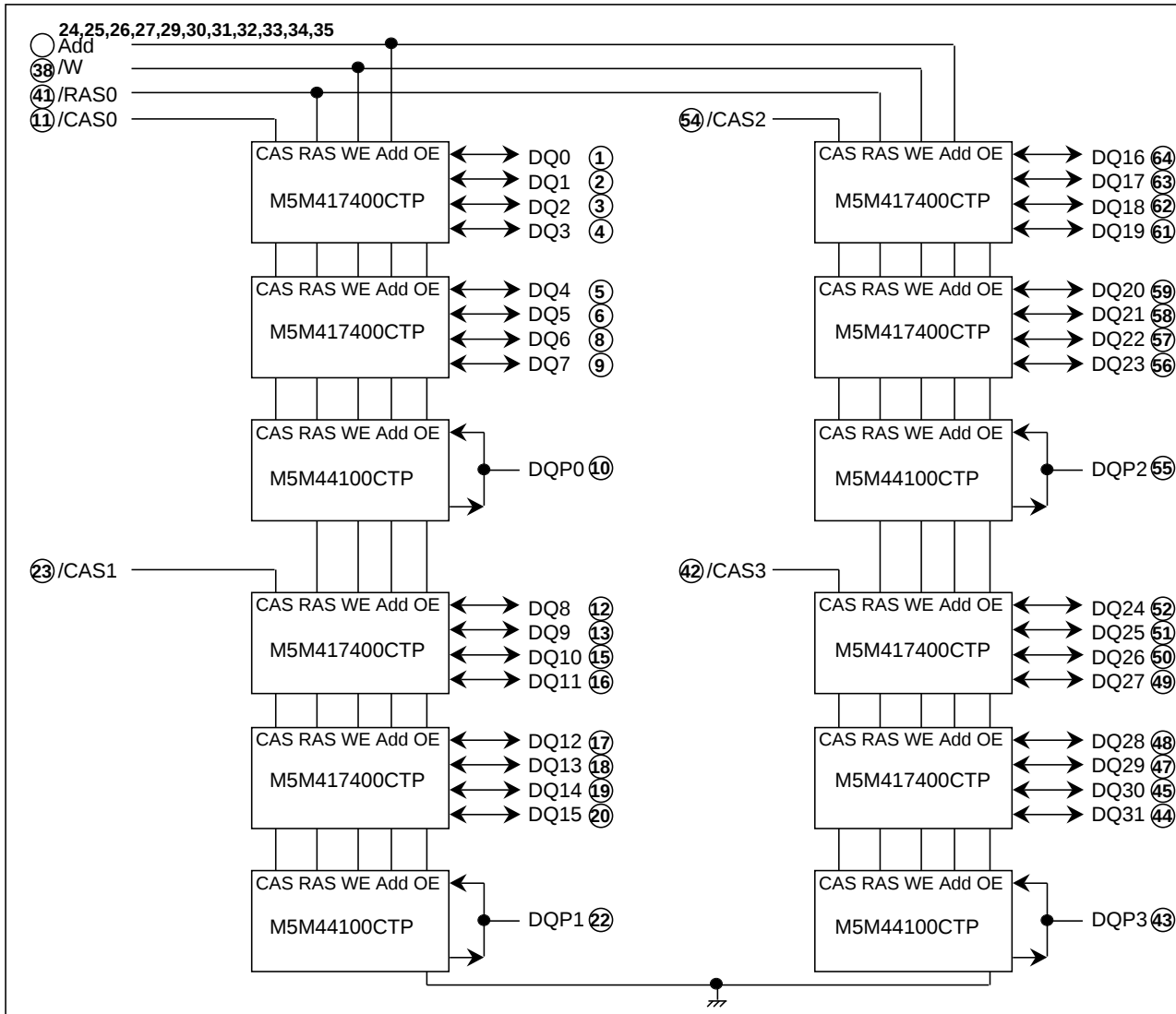
The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs						Input/Output		Refresh	Remark
	RAS	CAS	W	OE	Row address	Column address	Input	Output		
Read	ACT	ACT	NAC	ACT	APD	APD	OPN	VLD	YES	Fast page mode identical
Write (Early write)	ACT	ACT	ACT	DNC	APD	APD	APD	OPN	YES	
$\overline{\text{RAS}}$ -only refresh	ACT	NAC	DNC	DNC	APD	DNC	DNC	OPN	YES	
Hidden refresh	ACT	ACT	DNC	ACT	DNC	DNC	OPN	VLD	YES	
CAS before RAS refresh	ACT	ACT	NAC	DNC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : Invalid, APD : applied, OPN : open

BLOCK DIAGRAM



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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1 ~ 7	V
V _I	Input voltage		-1 ~ 7	V
V _O	Output voltage		-1 ~ 7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a =25°C	12	W
T _{opr}	Operating temperature		0 ~ 70	°C
T _{stg}	Storage temperature		-40 ~ 125	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0 ~ 70 °C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.0	V
V _{IL}	Low-level input voltage, all inputs	-1.0		0.8	V

Note 1 : All voltage values are with respect to V_{SS}

ELECTRICAL CHARACTERISTICS (T_a=0 ~ 70 °C, V_{CC}=5V ± 10%, V_{SS}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter		Test conditions	Limits			Unit
				Min	Typ	Max	
V _{OH}	High-level output voltage		I _{OH} =-5mA	2.4		V _{CC}	V
V _{OL}	Low-level output voltage		I _{OL} =4.2mA	0		0.4	V
I _{OZ}	Off-state output current		Q floating 0V ≤ V _{OUT} ≤ 5.5V	-10		10	μA
I _I	Input current		0V ≤ V _{IN} ≤ 6.0V, Other inputs pins=0V	-120		120	μA
I _{CC1} (AV)	Average supply current from V _{CC} operating (Note 3,4)	MH4M36CJD-5	RAS, CAS cycling			1660	mA
		MH4M36CJD-6	t _{RC} =t _{WC} =min. output open			1360	
		MH4M36CJD-7				1180	
I _{CC2}	Supply current from V _{CC} , stand-by		RAS= CAS =V _{IH} , output open			24	mA
			RAS= CAS ≥ V _{CC} -0.5			12	
I _{CC3} (AV)	Average supply current from V _{CC} refreshing (Note 3)	MH4M36CJD-5	RAS cycling, CAS= V _{IH}			1660	mA
		MH4M36CJD-6	t _{RC} =min. output open			1360	
		MH4M36CJD-7				1180	
I _{CC4} (AV)	Average supply current from V _{CC} Fast-Page-Mode (Note 3,4)	MH4M36CJD-5	RAS=V _{IL} , CAS cycling			1060	mA
		MH4M36CJD-6	t _{PC} =min. output open			900	
		MH4M36CJD-7				780	
I _{CC6} (AV)	Average supply current from V _{CC} CAS before RAS refresh mode (Note 3)	MH4M36CJD-5	CAS before RAS refresh cycling			1580	mA
		MH4M36CJD-6	t _{RC} =min. output open			1300	
		MH4M36CJD-7				1140	

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1} (AV), I_{CC3} (AV), I_{CC4} (AV) and I_{CC6} (AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: I_{CC1} (AV) and I_{CC4} (AV) are dependent on output loading. Specified values are obtained with the output open.

CAPACITANCE (T_a=0 ~ 70 °C, V_{CC}=5V ± 10%, V_{SS}=0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _I (A)	Input capacitance, address inputs	V _I =V _{SS} f=1MHz V _I =25mVrms			90	pF
C _I (W)	Input capacitance, write control input				130	pF
C _I (RAS)	Input capacitance, RAS input				130	pF
C _I (CAS)	Input capacitance, CAS input				35	pF
C _{I/O}	Input/Output capacitance, data ports				20	pF

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SWITCHING CHARACTERISTICS (Ta=0 ~ 70 °C, Vcc=5V ± 10%, Vss=0V, unless otherwise noted, see notes 5,12,13)

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
tCAC	Access time from $\overline{\text{CAS}}$ (Note 6,7)		13		15		20	ns
tRAC	Access time from $\overline{\text{RAS}}$ (Note 6,8)		50		60		70	ns
tAA	Column address access time (Note 6,9)		25		30		35	ns
tCPA	Access time from $\overline{\text{CAS}}$ precharge (Note 6,10)		30		35		40	ns
tCLZ	Output low impedance time from $\overline{\text{CAS}}$ low (Note 6)	5		5		5		ns
tOFF	Output disable time after $\overline{\text{CAS}}$ high (Note 11)	0	13	0	15	0	15	ns

Note 5: An initial pause of 500us is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a $\overline{\text{RAS}}$ clock such as $\overline{\text{RAS}}$ -Only refresh).

Note the $\overline{\text{RAS}}$ may be cycled during the initial pause. And any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS/CAS}}$ cycles are required after prolonged periods (greater than 32 ms) of $\overline{\text{RAS}}$ inactivity before proper device operation is achieved.

6: Measured with a load circuit equivalent to 2TTL loads and 100pF.

7: Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$ and $t_{\text{ASC}} \geq t_{\text{ASC}}(\text{max})$.

8: Assumes that $t_{\text{RCD}} \leq t_{\text{RCD}}(\text{max})$ and $t_{\text{RAD}} \leq t_{\text{RAD}}(\text{max})$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} exceeds the value shown.

9: Assumes that $t_{\text{RAD}} \geq t_{\text{RAD}}(\text{max})$ and $t_{\text{ASC}} \leq t_{\text{ASC}}(\text{max})$.

10: Assumes that $t_{\text{CP}} \leq t_{\text{CP}}(\text{max})$ and $t_{\text{ASC}} \geq t_{\text{ASC}}(\text{max})$.

11: tOFF(max) and tOEZ(max) defines the time at which the output achieves the high impedance state ($|I_{\text{OUT}}| \leq 10 \mu\text{A}$) and is not reference to VOH(min) or VOL(max).

TIMING REQUIREMENTS (For Read, Write, Refresh, and Fast-Page Mode Cycles)

(Ta=0 ~ 70 °C, Vcc=5V ± 10%, Vss=0V, unless otherwise noted See notes 12,13)

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
tREF	Refresh cycle time		32		32		32	ms
tRP	RAS high pulse width	30		40		50		ns
tRCD	Delay time, RAS low to CAS low (Note14)	18	37	20	45	20	50	ns
tCRP	Delay time, CAS high to RAS low	10		10		10		ns
tRPC	Delay time, RAS high to CAS low	0		0		0		ns
tCPN	CAS high pulse width	10		10		10		ns
tRAD	Column address delay time from RAS low (Note15)	13	25	15	30	15	35	ns
tASR	Row address setup time before RAS low	0		0		0		ns
tASC	Column address setup time before CAS low (Note16)	0	10	0	10	0	10	ns
tRAH	Row address hold time after RAS low	8		10		10		ns
tCAH	Column address hold time after CAS low	13		15		15		ns
tDZC	Delay time, data to CAS low (Note17)	0		0		0		ns
tCDD	Delay time, CAS high to data (Note18)	13		15		15		ns
tT	Transition time (Note19)	1	50	1	50	1	50	ns

Note 12: The timing requirements are assumed $t_T = 5\text{ns}$.

13: VIH(min) and VIL(max) are reference levels for measuring timing of input signals.

14: tRCD(max) is specified as a reference point only. If tRCD is less than tRCD(max), access time is tRAC. If tRCD is greater than tRCD(max), access time is controlled exclusively by tCAC or tAA. tRCD(min) is specified as $t_{\text{RCD}}(\text{min}) = t_{\text{RAH}}(\text{min}) + 2t_{\text{H}} + t_{\text{ASC}}(\text{min})$.

15: tRAD(max) is specified as a reference point only. If tRAD $\geq$ tRAD(max) and tASC $\leq$ tASC(max), access time is controlled exclusively by tAA.

16: tASC(max) is specified as a reference point only. If tRCD $\geq$ tRCD(max) and tASC $\geq$ tASC(max), access time is controlled exclusively by tCAC.

17: Either tDZC or tDZO must be satisfied.

18: Either tCDD or tODD must be satisfied.

19: tT is measured between VIH(min) and VIL(max).

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Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
t _{RC}	Read cycle time	90		110		130		ns
t _{RAS}	RAS iow pulse width	50	10000	60	10000	70	10000	ns
t _{CAS}	CAS iow pulse width	13	10000	15	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS iow	50		60		70		ns
t _{RSH}	RAS hold time after CAS iow	13		15		20		ns
t _{RCS}	Read Setup time after CAS high	0		0		0		ns
t _{RCH}	Read hold time after CAS iow (Note 20)	0		0		0		ns
t _{RRH}	Read hold time after RAS iow (Note 20)	10		10		10		ns
t _{RAL}	Column address to RAS hold time	25		30		35		ns

Note 20: Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.**Write Cycle**

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
t _{WC}	Write cycle time	90		110		130		ns
t _{RAS}	RAS iow pulse width	50	10000	60	10000	70	10000	ns
t _{CAS}	CAS iow pulse width	13	10000	15	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS iow	50		60		70		ns
t _{RSH}	RAS hold time after CAS iow	13		15		20		ns
t _{WCS}	Write setup time before CAS iow	0		0		0		ns
t _{WCH}	Write hold time after CAS iow	8		10		15		ns
t _{CWL}	CAS hold time after W iow	13		15		20		ns
t _{RWL}	RAS hold time after W iow	13		15		20		ns
t _{WP}	Write pulse width	8		10		15		ns
t _{DS}	Data setup time before CAS iow or W iow	0		0		0		ns
t _{DH}	Data hold time after CAS iow or W iow	8		10		15		ns

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Fast-Page Mode Cycle (Read, Early Write Cycle) (Note 21)

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
tPC	Fast page mode read/write cycle time	40		45		50		ns
tRAS	RAS low pulse width for read write cycle (Note22)	95	125000	110	125000	125	125000	ns
tCAS	CAS high pulse width (Note23)	8	12	10	15	10	15	ns
tCPRH	RAS hold time after CAS precharge	35		40		45		ns
tCPWD	Delay time, CAS precharge to W low	53		60		65		ns

Note 21: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

22: t_{RAS(min)} is specified as two cycles of CAS input are performed.

23: t_{CP(max)} is specified as a reference point only.

CAS before RAS Refresh Cycle (Note 24)

Symbol	Parameter	Limits						Unit
		MH4M36CJD-5		MH4M36CJD-6		MH4M36CJD-7		
		Min	Max	Min	Max	Min	Max	
tCSR	CAS setup time before RAS low	10		10		10		ns
tCHR	CAS hold time after RAS low	10		10		15		ns
tRSR	Read setup time before RAS low	10		10		10		ns
tRHR	Read hold time after RAS low	10		10		15		ns

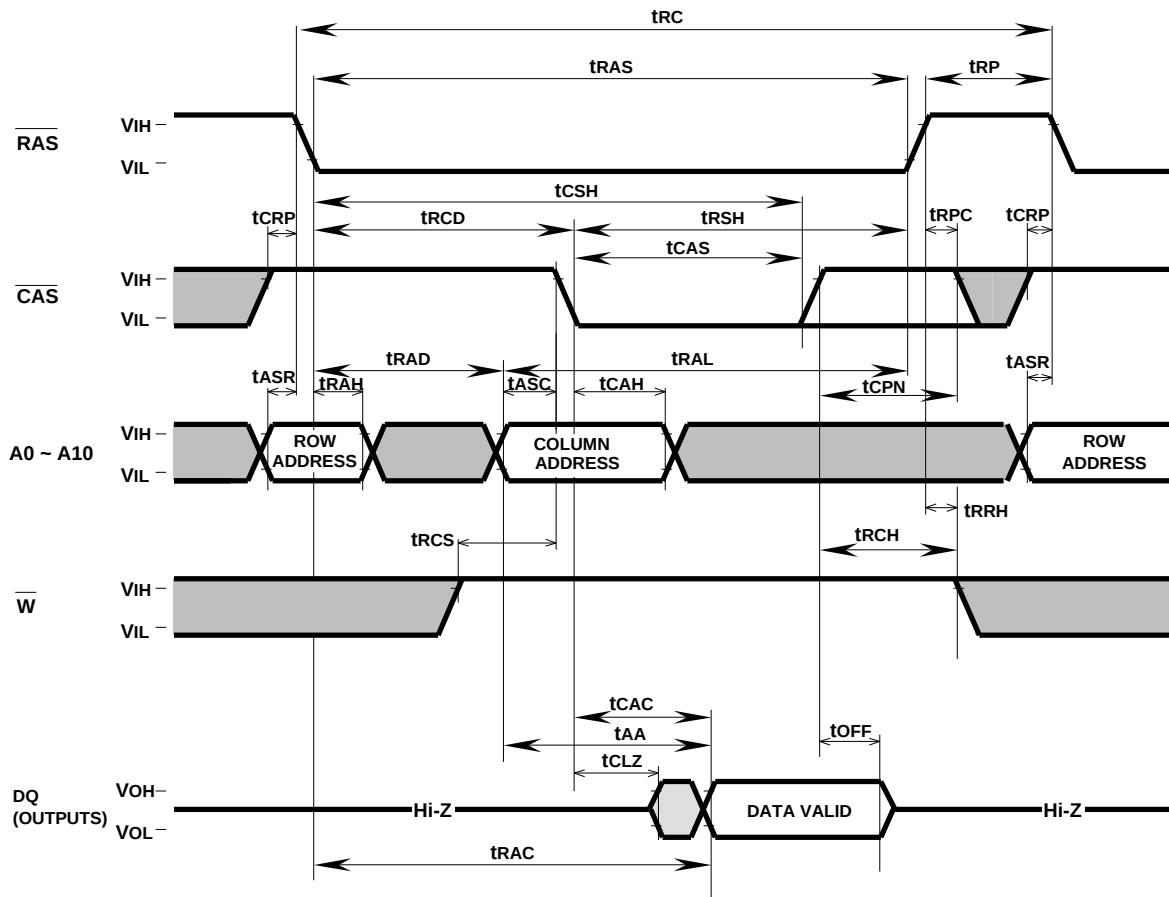
Note 24: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

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Timing Diagrams (Note 25)

Read Cycle



Note 25



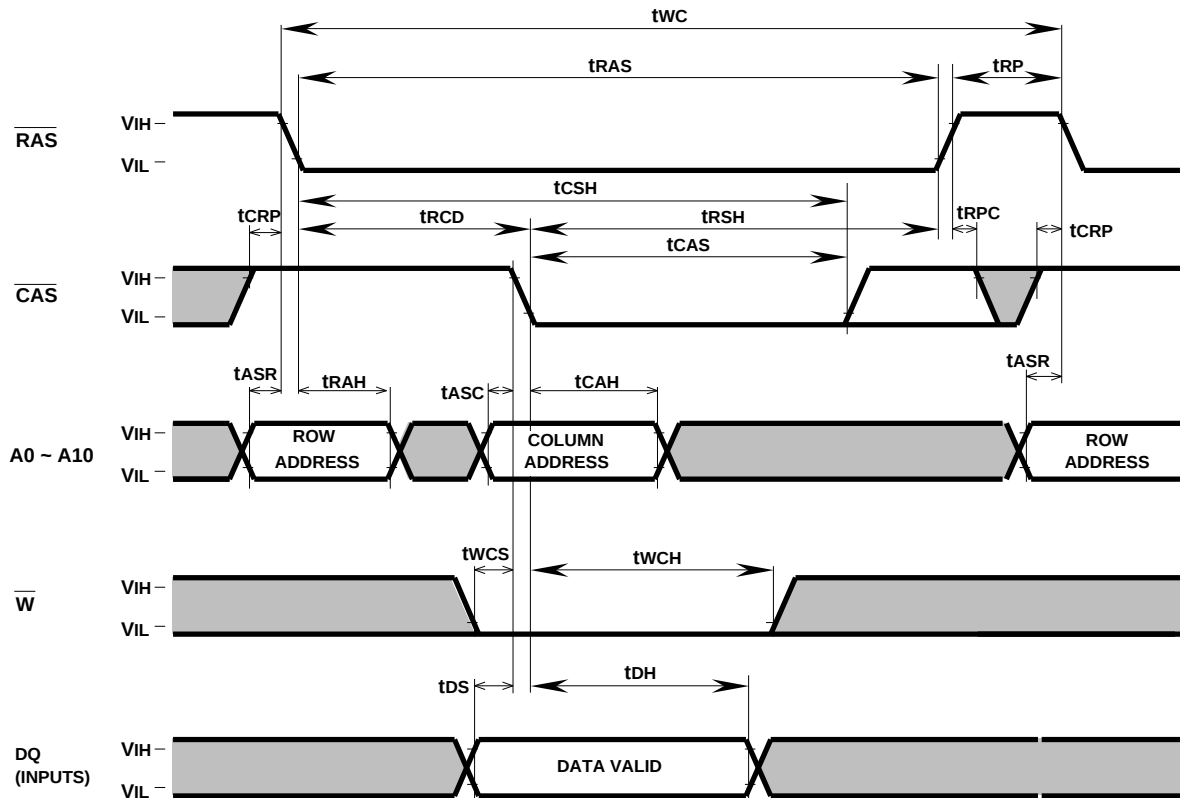
Indicates the don't care input.
 $V_{IH(min)} \leq V_{IN} \leq V_{IH(max)}$ or $V_{IL(min)} \leq V_{IN} \leq V_{IL(max)}$

Indicates the invalid output.

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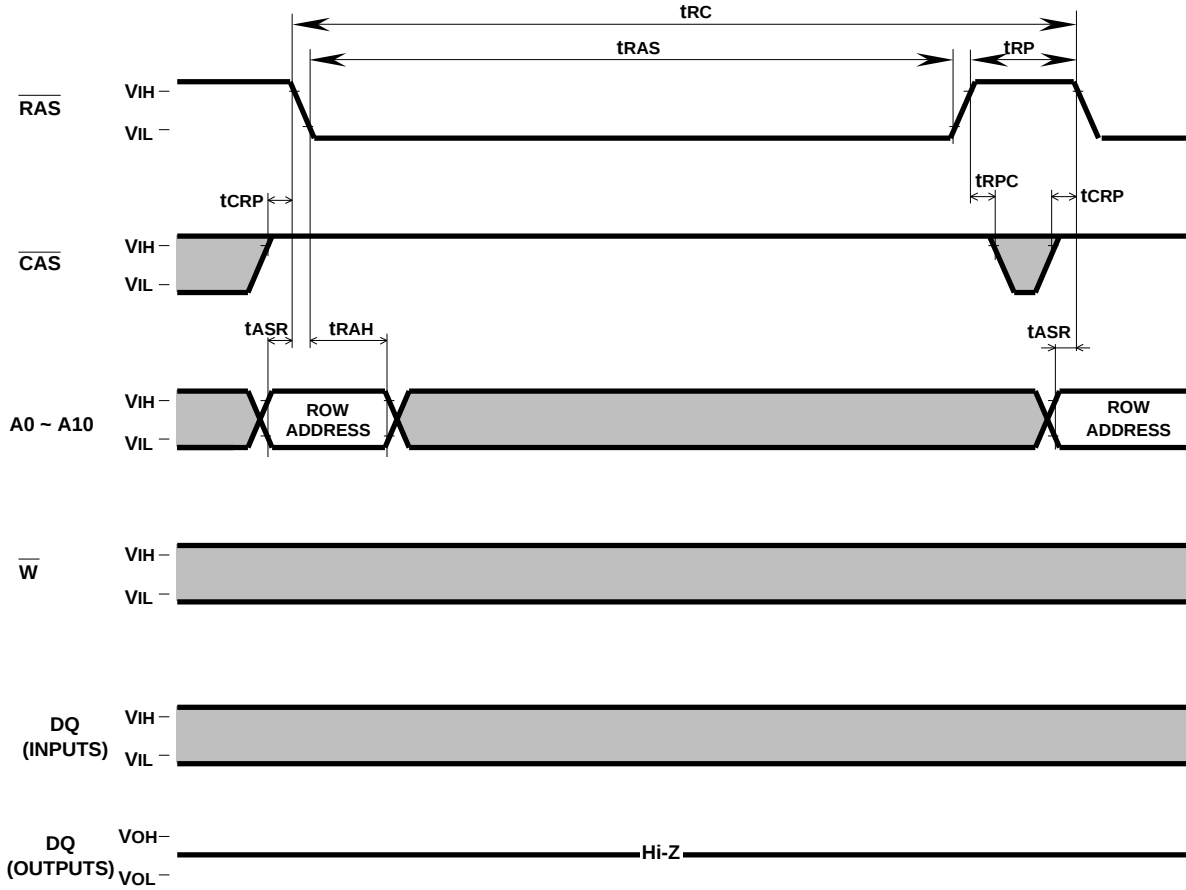
Write Cycle (Early write)



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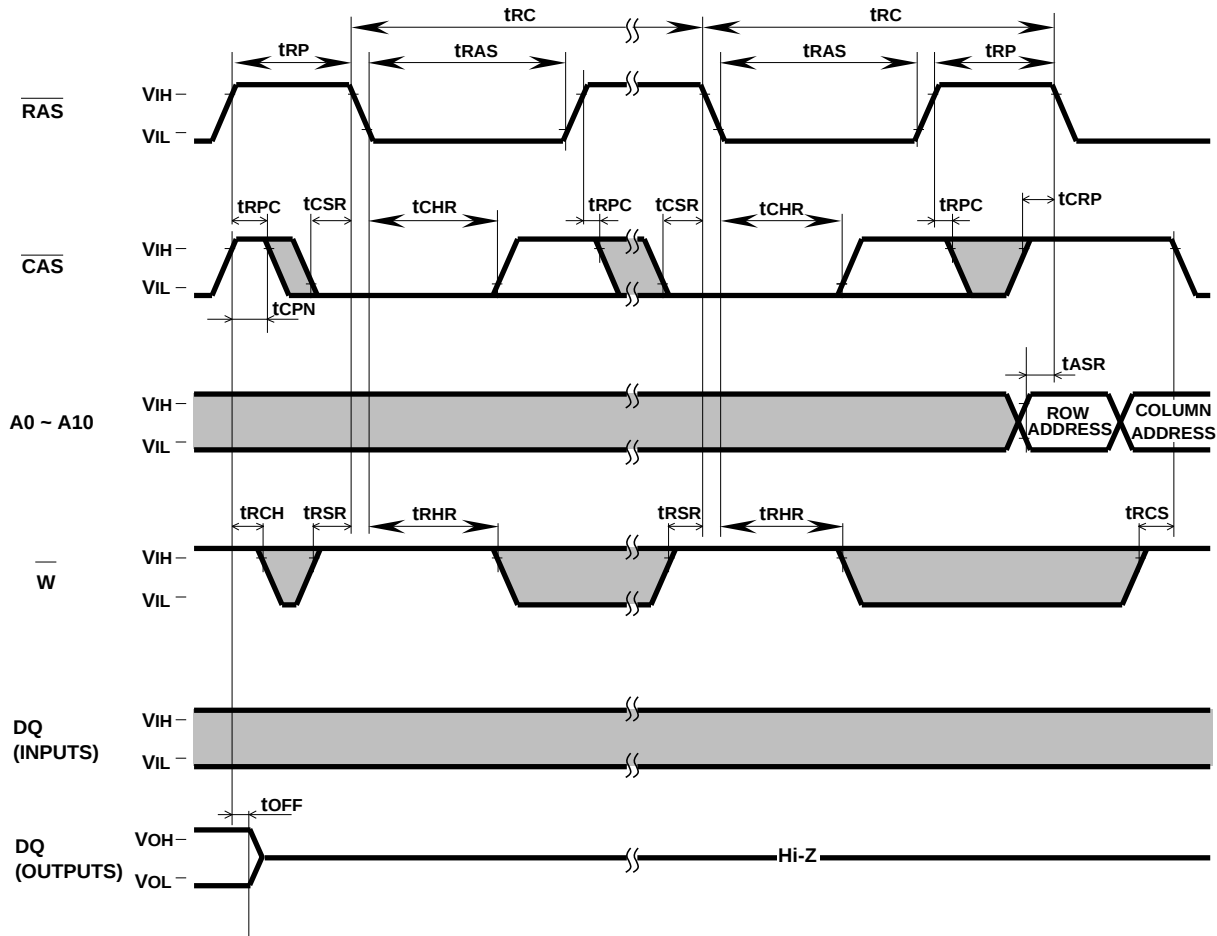
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RAS-only Refresh Cycle



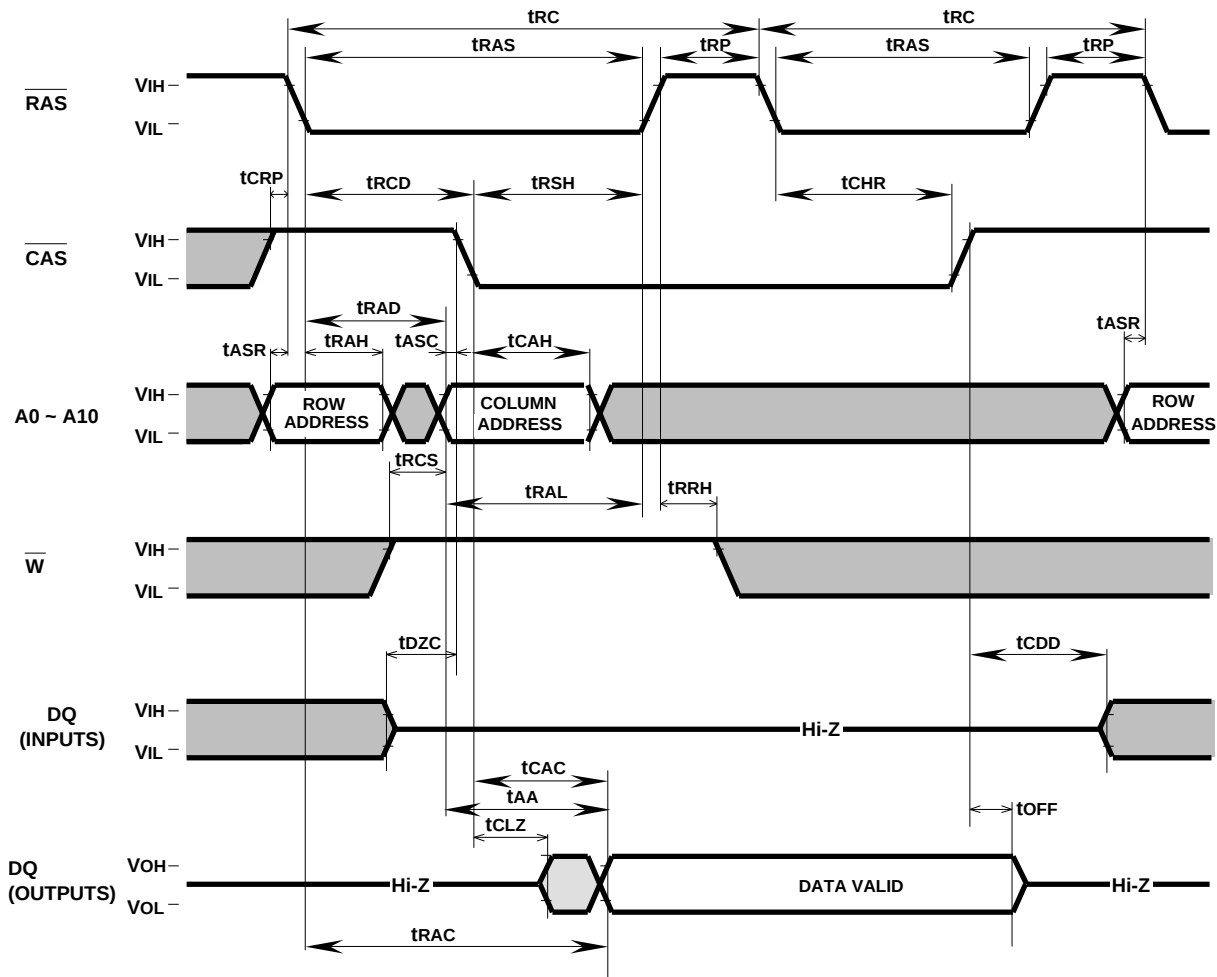
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 $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh Cycle

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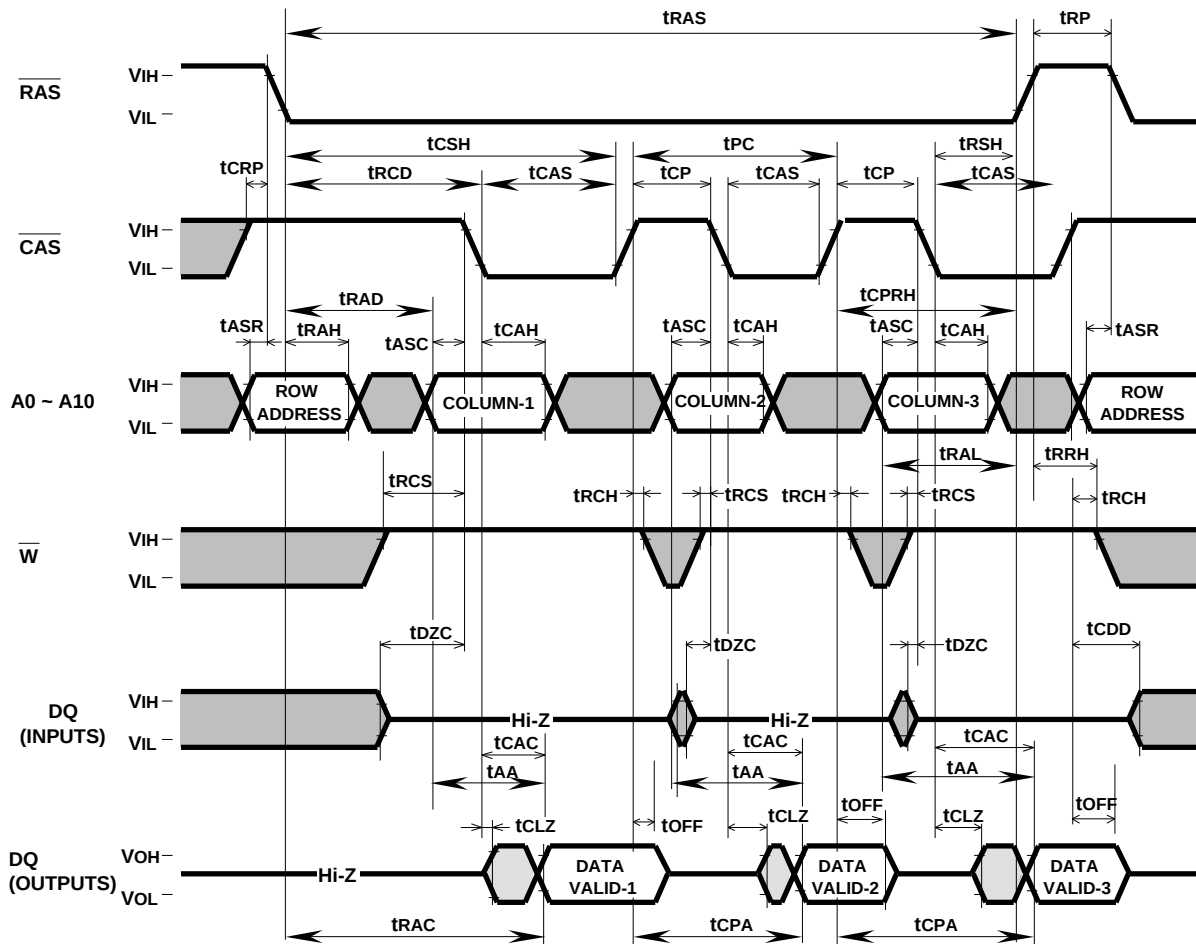
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Hidden Refresh Cycle (Read) (Note 26)

Note 26: Early write cycle is applicable instead of read cycle.
Timing requirements and output state are the same as that of each cycle shown above.

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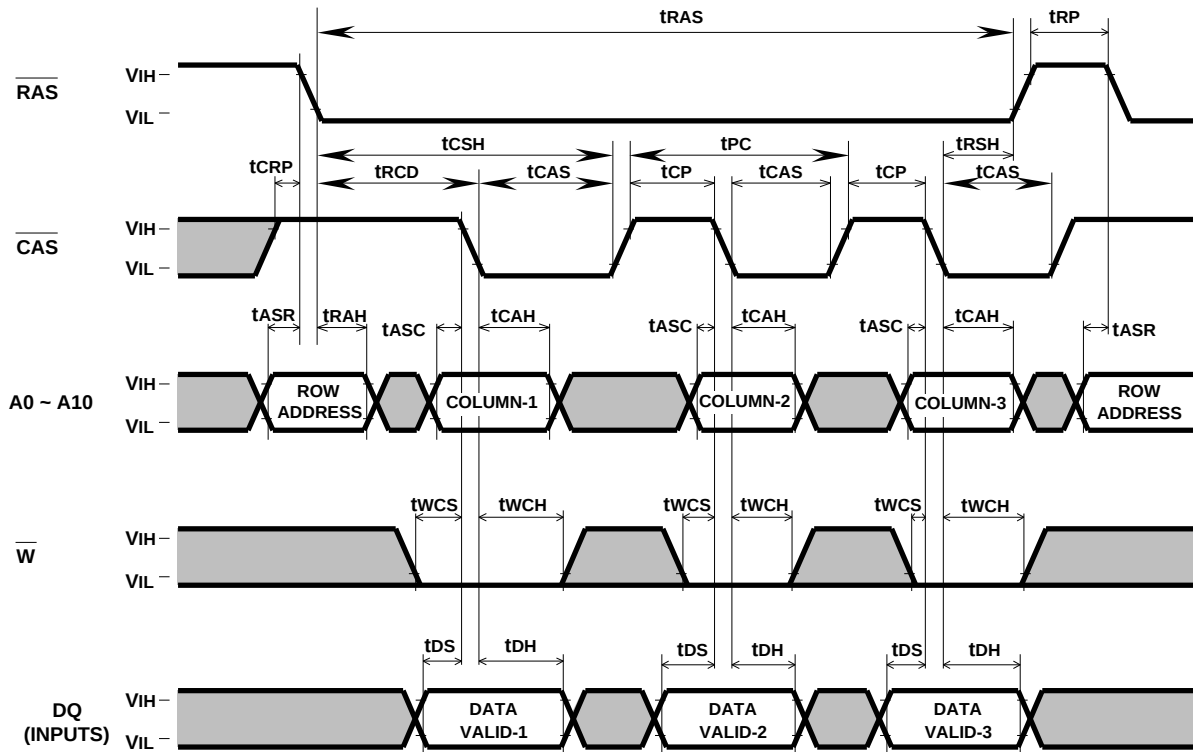
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Fast Page Mode Read Cycle

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Fast Page Mode Write Cycle (Early Write)



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